



NAND MCP Silicon Improvement: Bond Pad Metallization Change

PCN: 33253

Published: 2019-06-25

Revision History:

Revision 1, 2019-09-23: This document supersedes the original PCN #33253, dated 2019-06-25. Update to the "Description of Change" section includes a second table that reflects corrections to Qual/Sample Available and Product Ship dates, and verbiage updated to reflect the June 2020 date - identified by **bold** font. Also, Product Ship Date in the PCN now reflects June 30, 2020.

Type: Manufacturing Process Change

Description: Micron will convert the NAND bond pad metallization from Ni/Pd to Aluminum (Al). Other DRAM/NAND technologies at Fab 6 use Al bond process and is proven to be more robust.

During the conversion period, customers will receive a mix of both bond pad types, however, the change will not impact the final packaged products. Micron has complete traceability via Lot ID number, Sales Order number, or Purchase Order number, etc. Full conversion to the new process is planned by **June 2020**. Micron reserves the right to ship either ALM2 or NiPd manufactured until the NiPd inventory has been depleted.

WAS	IS
Layers:	Layers:
Metal 2: Cu + Ni/Pd (Plating)	Metal 2: Al (Sputter)

Product	Qual/Sample Available	Product Ship Date
J4Q2	7/31/2019	6/30/2020
J4MK	7/31/2019	6/30/2020
J84F	12/2/2019	6/30/2020

Reason: Improved Product Quality and Reliability, Manufacturing Efficiency

Product Affected: NAND MCP (J4Q2, J4MK, J84F)

Affected Micron Part Number Component	Recommended Replacement	Customer Part Number
MT29AZ5A3CHHWD-18AAT.84F		
MT29AZ5A3CHHWD-18AIT.84F		?
MT29C1G12MAAIVAMD-5 IT		
MT29C1G12MAAJVAMD-5 IT		557-1997-2-ND
MT29C4G48MAYBBAKS-48 IT		
MT29C4G48MAYBBAMR-48 IT		557-1998-2-ND
MT29C4G48MAZBBAKB-48 IT		557-1832-2-ND, ?
MT29C4G48MAZBBAKS-48 IT		557-1999-2-ND
MT29RZ4B2DZZHHWD-18I.84F		557-1889-2-ND

*Materials that have been ordered are in **bold**.

Method of Identification:	none
Micron Sites Affected:	Fab 6 - US
Sample Available:	2019-07-31
Qual Data Available:	2019-07-31
Product Ship Date:	2020-06-30

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

Micron Confidential and Proprietary Information

Attachments

There are no attachments on this PCN